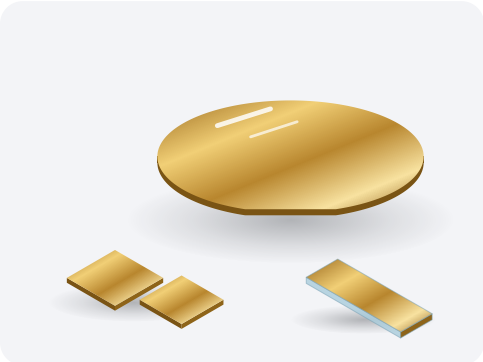
SERIES S50 · METAL-COATED

Metal-coated and plasmonic substrates



Sputtered or e-beam evaporated metal films on polished silicon, glass, fused silica or mica. Gold-on-glass chips are ready for surface plasmon resonance (SPR), SERS and self-assembled monolayer (SAM) work; gold on mica gives large atomically flat Au(111) terraces after annealing.

- Ti or Cr adhesion layers (2 – 10 nm)
- Roughness typically < 2 nm Rq on polished substrates
- Packed under nitrogen
- Other metals (Cu, Ni, Ti, W, Pd) and multilayers on request

CONFIGURATIONS

Ref. No.	Coating	Adhesion layer	Substrate	Format	Typical use	Price
S5001	Au 45 – 50 nm	Ti or Cr, 2 – 5 nm	Glass (n ≈ 1.52)	10 × 10 mm	SPR sensor chips	On request
S5002	Au 45 – 50 nm	Ti or Cr, 2 – 5 nm	Glass (n ≈ 1.52)	12 × 12 mm	SPR sensor chips	On request
S5003	Au 45 – 50 nm	Ti or Cr, 2 – 5 nm	Glass (n ≈ 1.52)	25 × 75 mm	SPR sensor chips	On request
S5004	Au 45 – 50 nm	Ti or Cr, 2 – 5 nm	Fused silica	10 × 10 mm	SPR sensor chips	On request
S5005	Au 45 – 50 nm	Ti or Cr, 2 – 5 nm	Fused silica	12 × 12 mm	SPR sensor chips	On request
S5006	Au 45 – 50 nm	Ti or Cr, 2 – 5 nm	Fused silica	25 × 75 mm	SPR sensor chips	On request
S5007	Au 100 nm	Ti, 5 – 10 nm	Si	10 × 10 mm chip	SERS, electrochemistry, SAMs	On request
S5008	Au 100 nm	Ti, 5 – 10 nm	Si	4" wafer	SERS, electrochemistry, SAMs	On request
S5009	Au 100 nm	Ti, 5 – 10 nm	SiO_2/Si	10 × 10 mm chip	SERS, electrochemistry, SAMs	On request
S5010	Au 100 nm	Ti, 5 – 10 nm	SiO_2/Si	4" wafer	SERS, electrochemistry, SAMs	On request
S5011	Au 100 nm	Ti, 5 – 10 nm	Glass	10 × 10 mm chip	SERS, electrochemistry, SAMs	On request
S5012	Au 100 nm	Ti, 5 – 10 nm	Glass	4" wafer	SERS, electrochemistry, SAMs	On request
S5013	Au 200 nm	Ti, 5 – 10 nm	Si	10 × 10 mm chip	SERS, electrochemistry, SAMs	On request
S5014	Au 200 nm	Ti, 5 – 10 nm	Si	4" wafer	SERS, electrochemistry, SAMs	On request
S5015	Au 200 nm	Ti, 5 – 10 nm	SiO_2/Si	10 × 10 mm chip	SERS, electrochemistry, SAMs	On request
S5016	Au 200 nm	Ti, 5 – 10 nm	SiO_2/Si	4" wafer	SERS, electrochemistry, SAMs	On request
S5017	Au 200 nm	Ti, 5 – 10 nm	Glass	10 × 10 mm chip	SERS, electrochemistry, SAMs	On request
S5018	Au 200 nm	Ti, 5 – 10 nm	Glass	4" wafer	SERS, electrochemistry, SAMs	On request
S5019	Au 200 nm	None	Muscovite mica	10 × 10 mm	Au(111) for STM / AFM	On request
S5020	Au 200 nm	None	Muscovite mica	25 × 25 mm	Au(111) for STM / AFM	On request
S5021	Ag 50 nm	Cr, 2 nm	Glass	10 × 10 mm chip	Plasmonics, SERS	On request
S5022	Ag 50 nm	Cr, 2 nm	Si	10 × 10 mm chip	Plasmonics, SERS	On request
S5023	Ag 100 nm	Cr, 2 nm	Glass	10 × 10 mm chip	Plasmonics, SERS	On request
S5024	Ag 100 nm	Cr, 2 nm	Si	10 × 10 mm chip	Plasmonics, SERS	On request
S5025	Al 50 nm	None	Si	10 × 10 mm chip	UV plasmonics, mirrors	On request
S5026	Al 50 nm	None	Fused silica	10 × 10 mm chip	UV plasmonics, mirrors	On request
S5027	Al 100 nm	None	Si	10 × 10 mm chip	UV plasmonics, mirrors	On request

Ref. No.	Coating	Adhesion layer	Substrate	Format	Typical use	Price
S5028	Al 100 nm	None	Fused silica	10 × 10 mm chip	UV plasmonics, mirrors	On request
S5029	Pt 100 nm	Ti, 10 nm	Si	10 × 10 mm chip	Electrochemistry, bottom electrodes	On request
S5030	Pt 100 nm	Ti, 10 nm	Si	4" wafer	Electrochemistry, bottom electrodes	On request
S5031	Pt 100 nm	Ti, 10 nm	SiO_2/Si	10 × 10 mm chip	Electrochemistry, bottom electrodes	On request
S5032	Pt 100 nm	Ti, 10 nm	SiO_2/Si	4" wafer	Electrochemistry, bottom electrodes	On request
S5033	Cr 100 nm	None	Glass	10 × 10 mm chip	Masks, adhesion studies	On request
S5034	Cr 100 nm	None	Si	10 × 10 mm chip	Masks, adhesion studies	On request

Specifications are typical values; every lot ships with a Certificate of Conformance, and measured data are available on request. Prices on request.